

Title (en)

DEVICE FOR THERMAL TREATMENT OF SUBSTRATES

Title (de)

VORRICHTUNG ZUM THERMISCHEN BEHANDELN VON SUBSTRATEN

Title (fr)

DISPOSITIF DE TRAITEMENT THERMIQUE DE SUBSTRATS

Publication

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Application

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Abstract (en)

[origin: WO0156064A1] The aim of the invention is to reduce the formation of scratches in a device for the thermal treatment of substrates, in particular, semiconductor substrates, in a chamber in which the substrate is placed upon support elements. According to the invention, said aim is achieved by means of displaceable support elements.

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